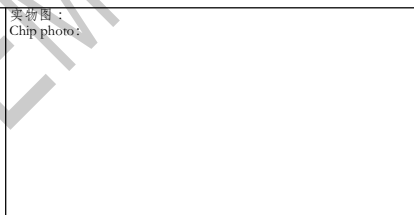
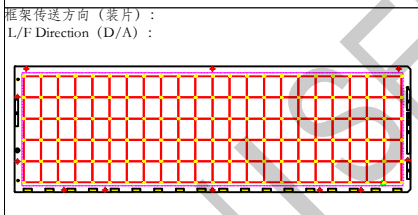
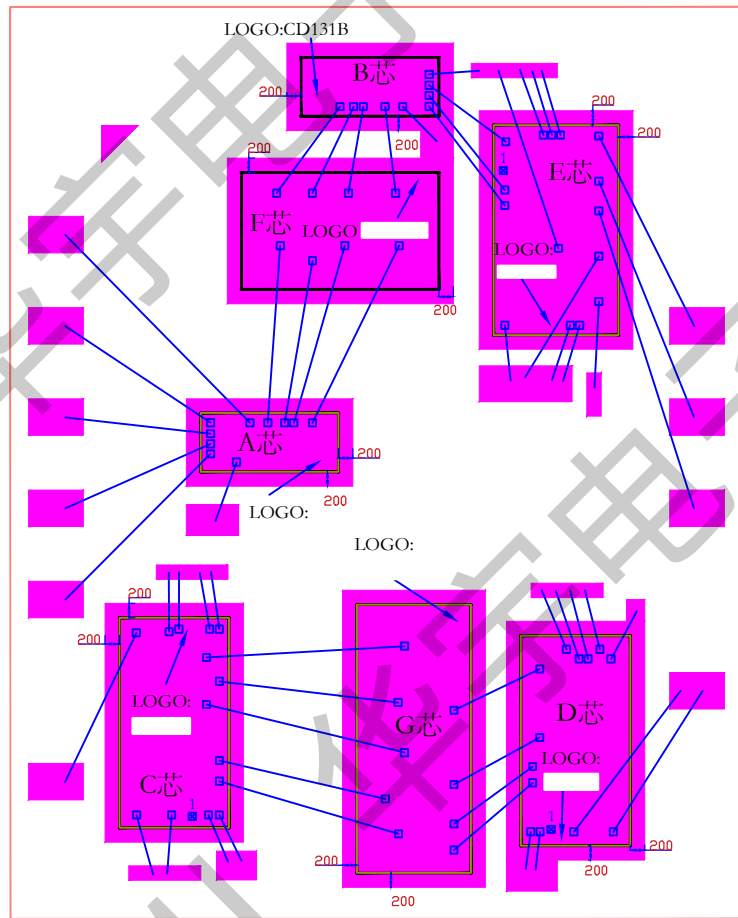
 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.	线图号 Drawing No.	页码 Page 1 / 2
产品名称 Product Type				封装外型 PKG Type		LGA16L(12.7×10.2×1.31-P1.27)
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)
金丝 Au	30			4350	529	首选(Preferred): G770 备选(Optional):
剪刀型号 Capillary Type			客户图号 Customer drawing NO.			



特殊说明 Special Instructions:


DB注意:
1.装片位置公差为±30μm;
2.控制溢胶,为WB预留焊线位置。

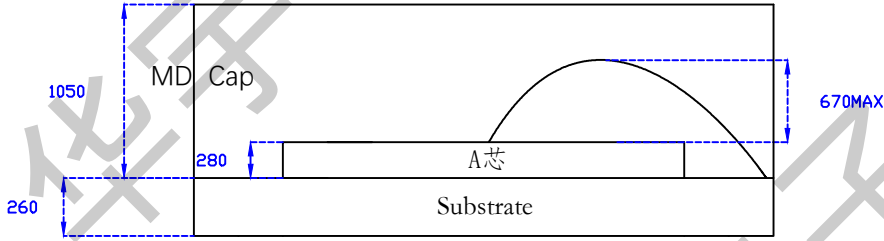
WB注意:
数字为不打线pad点个数。

说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BFO (μm²)	最小焊盘间距 Min BFP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否是 Low-K If low-k?	减薄厚度 (μm) Wafer Thickness
A芯: DIE A	导电胶 (conductivity) S820		700*180(μm²) 27.55*70.86(mil²)	100*100	128	2.3	否/NO	NA	6	否/NO	280 (客户要求)
B芯: DIE B	导电胶 (conductivity) S820		700*180(μm²) 27.55*70.86(mil²)	100*100	137	2.3	否/NO	NA	6	否/NO	280 (客户要求)
C芯: DIE C	导电胶 (conductivity) S820		1405*2805(μm²) 55.31*110.43(mil²)	100*100	133	2.3	否/NO	NA	6	否/NO	280 (客户要求)
D芯: DIE D	导电胶 (conductivity) S820		1405*2805(μm²) 55.31*110.43(mil²)	100*100	125	2.3	否/NO	NA	6	否/NO	280 (客户要求)
E芯: DIE E	导电胶 (conductivity) S820		1620*2805(μm²) 63.77*110.43(mil²)	100*100	130	2.3	否/NO	NA	6	否/NO	280 (客户要求)
F芯: DIE F	导电胶 (conductivity) S820		1510*2630(μm²) 59.44*103.54(mil²)	100*100	500	2.3	否/NO	NA	6	否/NO	280 (客户要求)
G芯: DIE G	导电胶 (conductivity) S820		1470*3620(μm²) 57.87*142.51(mil²)	100*100	364	2.3	否/NO	NA	6	否/NO	280 (客户要求)

制图日期 Create Date	生效日期 Effective Date	客户确认签字/盖章: Customer Signature	
拟制 Prepared by	审核 Checked by	批准 Approved by	

*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我可依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

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产品名称 Product Type				封装外型 PKG Type		LGA16L(12.7×10.2×1.31-P1.27)
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金丝 Au	30			4350	529	基板编码 Substrate No.
剪刀型号 Capillary Type			客户图号 Customer drawing NO.			



1	料号	型号规格	数量	位号
序号				

制图日期 Create Date	生效日期 Effective Date	客户确认签字/盖章: Customer Signature		
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